

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Canceled)
2. (Previously Presented) A wiring board comprising:
 - a substrate;
 - an interconnect layer formed of a plurality of layers, the interconnect layer being formed over the substrate, the plurality of layers being formed one over another at different levels in a thickness direction of the substrate, one of the plurality of layers having an interconnecting pattern positioned therein, the interconnecting pattern having at least three interconnecting lines disposed parallel to each other; and
 - a plurality of electrodes formed to overlap the interconnect layer;
 - wherein a part of a first interconnecting pattern and a part of a second interconnecting pattern are disposed to extend in directions forming a lattice under each of the electrodes, the first interconnecting pattern being positioned in a first layer among the plurality of layers forming the interconnect layer, the second interconnecting pattern being positioned in a second layer among the plurality of layers forming the interconnect layer.
3. (Previously Presented) A wiring board comprising:
 - a substrate;
 - an interconnect layer formed of a plurality of layers, the interconnect layer being formed over the substrate, the plurality of layers being formed one over another at different levels in a thickness direction of the one of the plurality of layers having an interconnecting pattern positioned therein, the interconnecting pattern having at least three interconnecting lines disposed parallel to each other; and
 - a plurality of electrodes formed to overlap the interconnect layer;

wherein first and second interconnecting patterns positioned respectively in first and second layers among the plurality of layers forming the interconnect layer have portions extending parallel to each other under each of the electrodes, and the parallel extending portions are formed not to overlap each other.

4-5. (Canceled)

6. (Original) The wiring board as defined in claim 2, further comprising:
an organic resin layer formed to cover the interconnect layer, and having an upper surface made flat,

wherein the electrodes are formed over the organic resin layer and are electrically connected to at least one of plurality of layers forming the interconnect layers by passing through the organic resin layer.

7. (Original) The wiring board as defined in claim 3, further comprising:
an organic resin layer formed to cover the interconnect layer, and having an upper surface made flat,

wherein the electrodes are formed over the organic resin layer and are electrically connected to at least one of plurality of layers forming the interconnect layers by passing through the organic resin layer.

8-9. (Canceled)

10. (Original) An electro-optical device comprising:
the wiring board as defined in claim 2; and
a functional layer for constituting an electro-optical element, the functional layer being formed in a first region of each of the electrodes;

wherein each of the electrodes and one of the plurality of layers forming the interconnect layer supplying power to the electrode are connected in a second region of the electrode.

11. (Original) An electro-optical device comprising:
the wiring board as defined in claim 3; and
a functional layer for constituting an electro-optical element, the functional layer being formed in a first region of each of the electrodes;
wherein each of the electrodes and one of the plurality of layers forming the interconnect layer supplying power to the electrode are connected in a second region of the electrode.

12-13. (Canceled)

14. (Original) An electronic instrument comprising the electro-optical device as defined in claim 10.

15. (Original) An electronic instrument comprising the electro-optical device as defined in claim 11.

16-34. (Canceled)